

Fig. 1

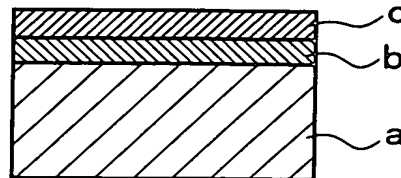
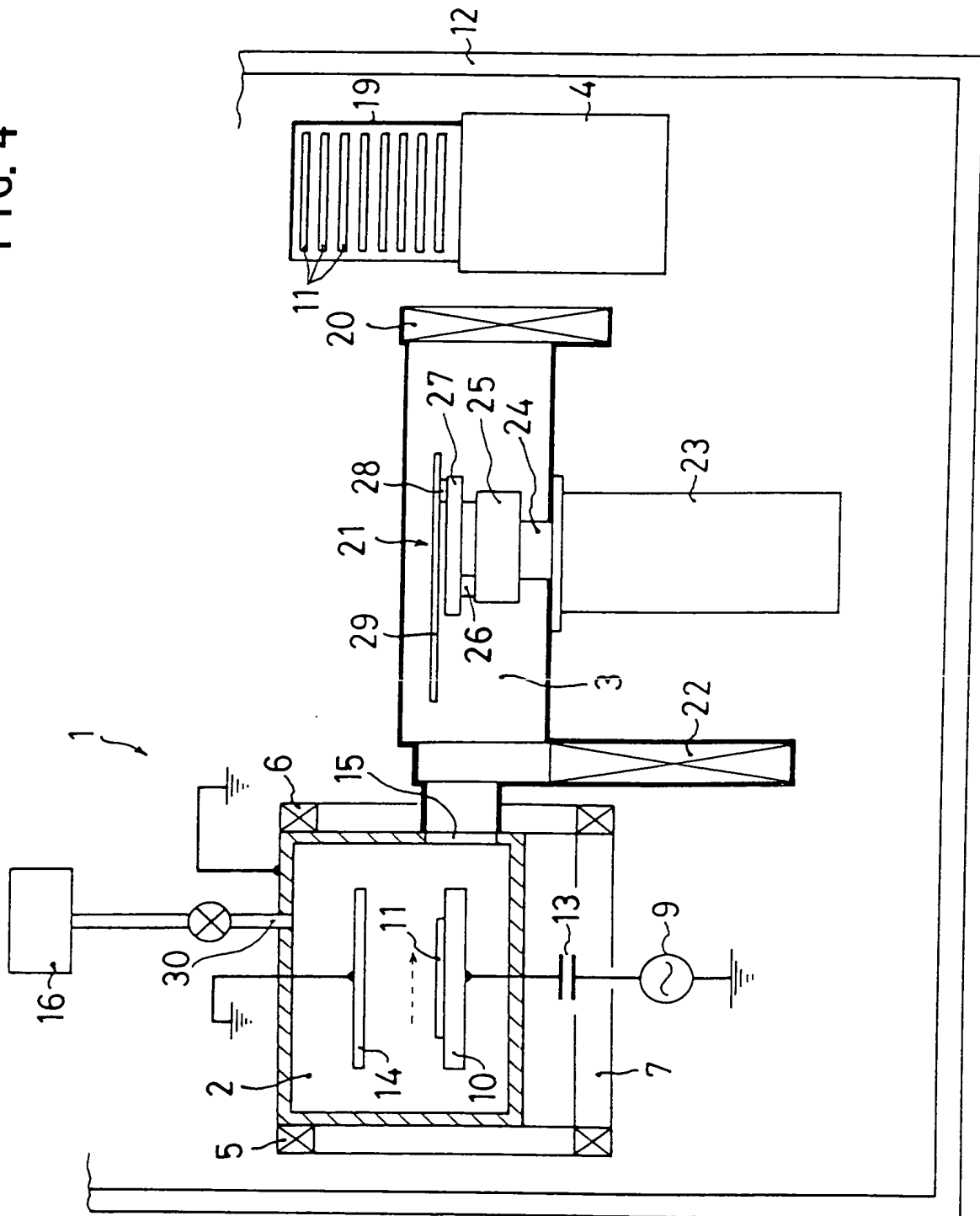


Fig. 2

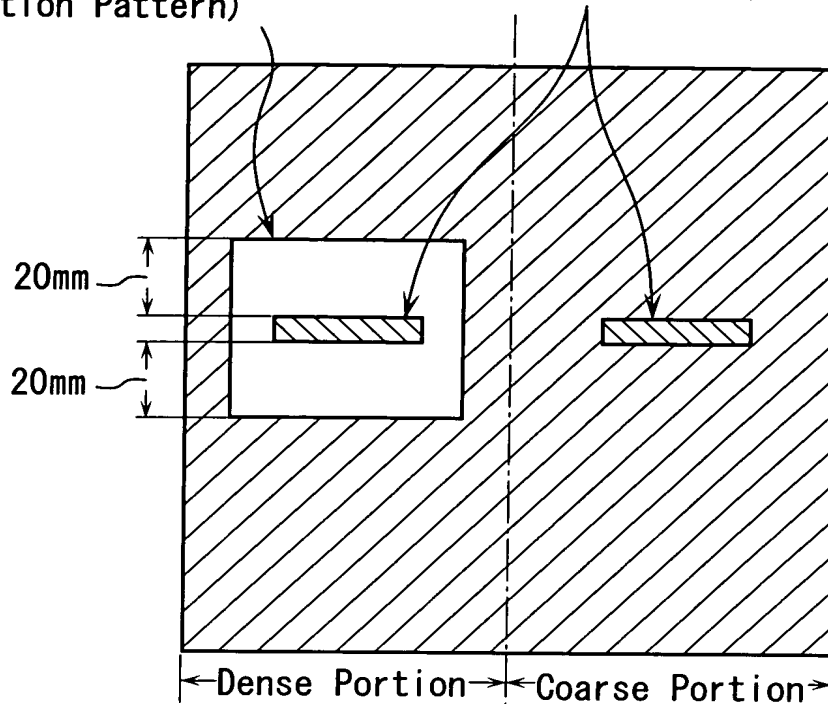
Flow	Electron Beam Patterning Process	Laser Beam Patterning Process
Receipt of Blank		
Exposure/Patterning	Electron Beam Patterning Device	Laser Beam Patterning Device
Development	Spray, Dip, Paddle Systems	
	Organic Solvent Development Alkali Development	Alkali Development
Post-Baking	Hot Plate Oven Convection Oven	Generally, any treatment is not required.
De-scumming	Plasma De-scumming Device	Generally, any treatment is not required.
CrEtching	Wet Etching and Dry-Etching	
Removal of Resist	Solvent Peeling, Ashing	Exposure of Whole Surface/Alkali Peeling, Solvent Peeling, Ashing
Washing	Sheet-Fed Acid-Treatment, Physical Scrubbing, or the like	
To Inspection Step		



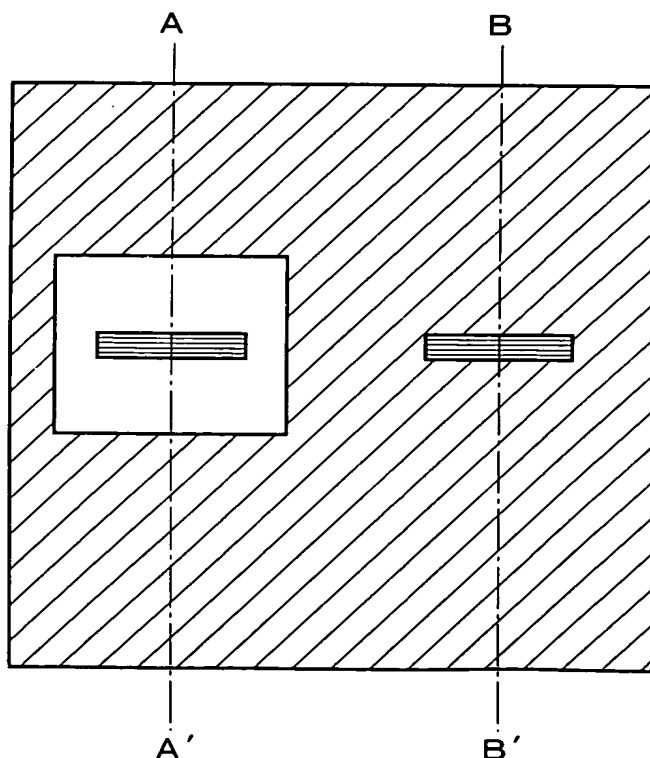
Fing. 5 A

Completely Removed Pattern
 (Periphery of the Dimension-
 Evaluation Pattern)

Dimension-Evaluation Pattern
 (L/S, Isolated L, Isolated S)



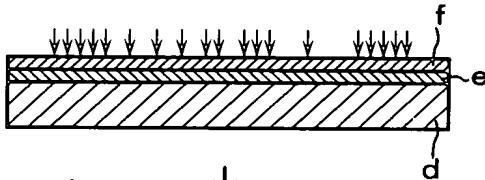
Fing. 5 B



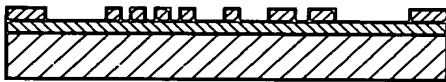
Fing. 6 A

Test Pattern on Dense Portion (A-A')

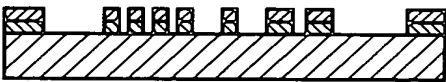
(a) EB Patterning



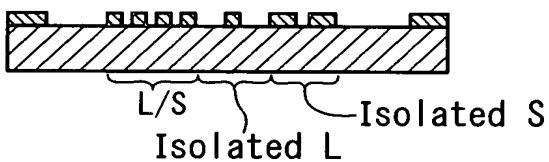
(b) Development ↓



(c) Etching ↓



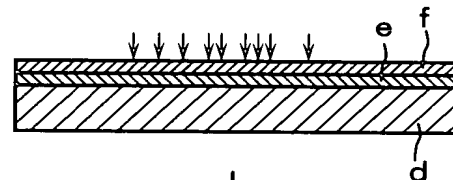
(d) Removal of Resist ↓



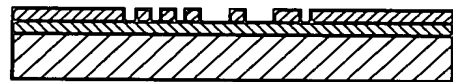
Fing. 6 B

Test Pattern on Coarse Portion (B-B')

(a) EB Patterning



(b) Development ↓



(c) Etching ↓



(d) Removal of Resist ↓

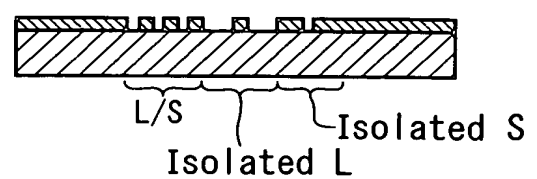
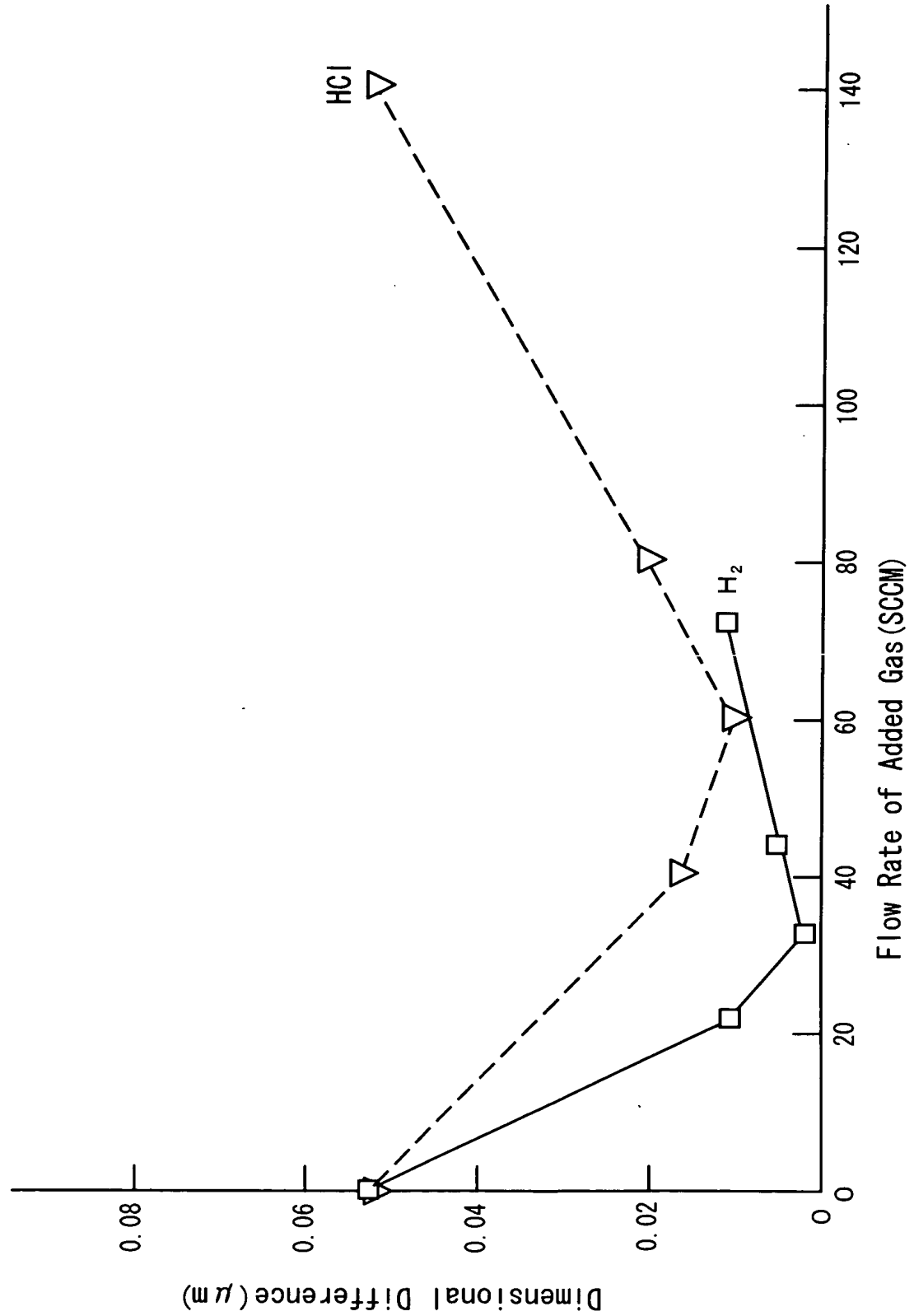


Fig. 7



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Fig. 8

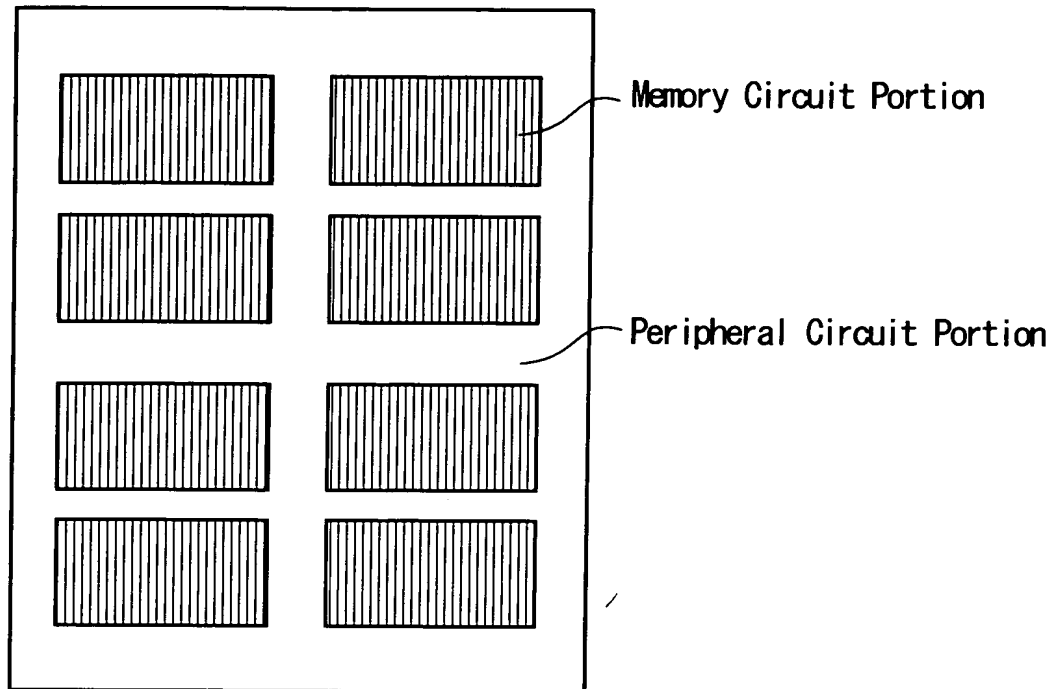


Fig. 9

